# Abstracts

## Three-Dimensional Passive Circuit Technology for Ultra-Compact MMICs (1995 Vol. III [MWSYM])

*M. Hirano, K. Nishikawa, I. Toyoda, S. Aoyama, S. Sugitani and K. Yamasaki. "Three-Dimensional Passive Circuit Technology for Ultra-Compact MMICs (1995 Vol. III [MWSYM])." 1995 MTT-S International Microwave Symposium Digest 95.3 (1995 Vol. III [MWSYM]): 1447-1450.*

A novel passive circuit technology of a three-dimensional (3D) metal-insulator structure has been developed for ultra-compact MMICS. By combining vertical passive elements, such as a wall-like microwire for shielding or coupling and a pillar-like via connection, with multilayer passive circuits, highly dense and more functional MMICS can be implemented.

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